

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3870792

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
BENJAMIN STASSEN COOK	05/09/2016
ROBERTO GIAMPIERO MASSOLINI	05/09/2016
DANIEL CAROTHERS	05/09/2016
RECEIVING PARTY DATA	
Name:	TEXAS INSTRUMENTS INCORPORATED
Street Address:	12500 TI BOULEVARD
Internal Address:	MS 3999
City:	DALLAS
State/Country:	TEXAS
Postal Code:	75243
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15152518
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Correspondent Name:	TEXAS INSTRUMENTS INCORPORATED
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Address Line 4:	DALLAS, TEXAS 75265
ATTORNEY DOCKET NUMBER:	TI-76798
NAME OF SUBMITTER:	GERALD E LAWS
SIGNATURE:	/Gerald E Laws 39268/
DATE SIGNED:	05/12/2016
Total Attachments: 3	
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source=TI-76798-ASG#page2.tif	

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made.

WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with a place of business at 12500 TI Boulevard - M/S 3999, Dallas, Texas 75243, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign unto the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in and to the said application(s) and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Patent and Trademark Office to issue all patents for said invention, or patents resulting therefrom, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.

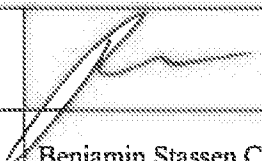
I also hereby sell and assign to TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my corresponding rights to the invention disclosed in said application in all other countries of the world, including the right to claim priority, file applications and obtain patents under the terms of the Paris Convention for the Protection of Industrial Property, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such rights.


I hereby further agree that I will communicate to said TEXAS INSTRUMENTS INCORPORATED, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

I authorize the later insertion of the nonprovisional application number and filing date herein below.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year:

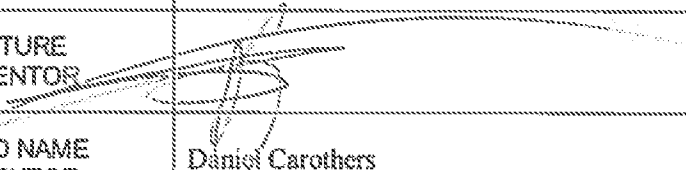
TITLE	Semiconductor Die with Back-Side Integrated Inductive Component		
NONPROVISIONAL APPLICATION NO.	15/152,518	FILING DATE	May 11, 2016

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Benjamin Stassen Cook
DATE	5/9/2016
RESIDENCE (CITY, STATE and COUNTRY)	Addison, TX, USA

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Roberto Giampiero Massolini
DATE	9 MAY 2016
RESIDENCE (CITY, PROVINCE and COUNTRY)	Pavia, PV, Italy
SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Daniel Carothers
DATE	
RESIDENCE (CITY, STATE and COUNTRY)	Lucas, TX, USA

After recording, return Assignment to:

Texas Instruments Incorporated
PO Box 655474, M/S 3999
Dallas, TX 75265

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Roberto Giampiero Masssolini
DATE	
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SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Daniel Carothers
DATE	5/7/12
RESIDENCE (CITY, STATE and COUNTRY)	Lucas, TX, USA

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